

SD-MSS-1K series

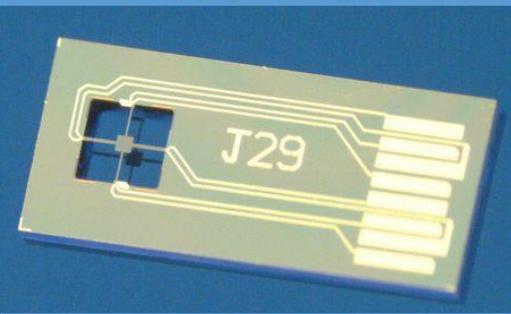
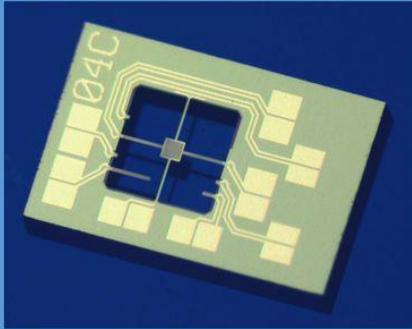
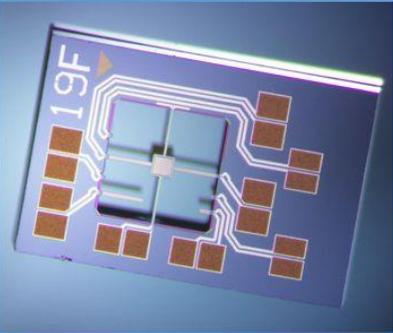
Device information

SD-MSS-1KTM

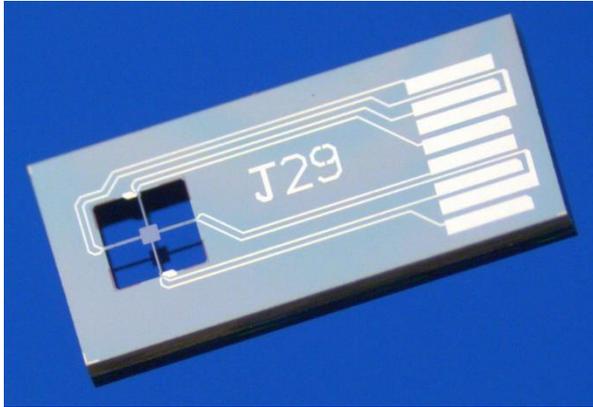
SD-MSS-1KPMAI

SD-MSS-1KPMAu

for Torque Magnetometry in DC/Pulsed Field

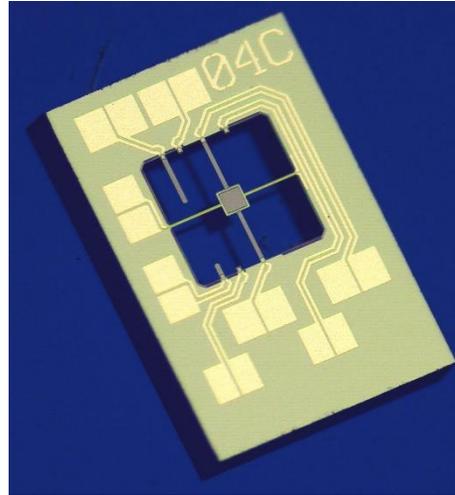
Code	 <p>SD-MSS-1KTM</p>	 <p>SD-MSS-1KPMAl</p>	 <p>SD-MSS-1KPMAlu</p>
Membrane size [μm]	200 square		200 square with coil
Membrane thickness [μm]	2.8 (typical)		
Chip dimensions [mm]	5.5 x 2.5 x 0.3		3.0 x 2.0 x 0.3
Resistance value [kΩ]	0.3 – 1.2		
Electric configuration	Separated, 8 pads 0.25 (0.5) mm pitch	Aluminum pads for wire bonding or gluing	Gold pads for wire bonding or gluing
Piezoresistive cantilever	No		120 μm, 400 μm

SD-MSS-1KTM



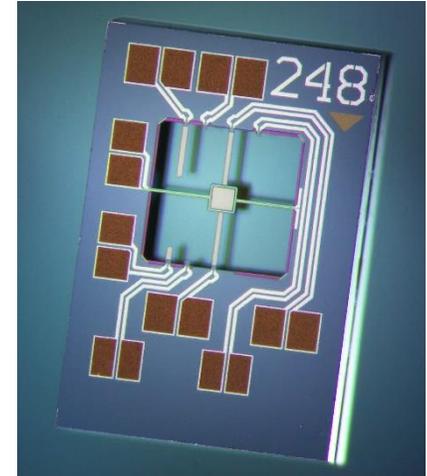
- Reasonable chip size for comfortable handing
- Easy socket connection
- Possibility of changing structure by breaking beams

SD-MSS-1KPMAl

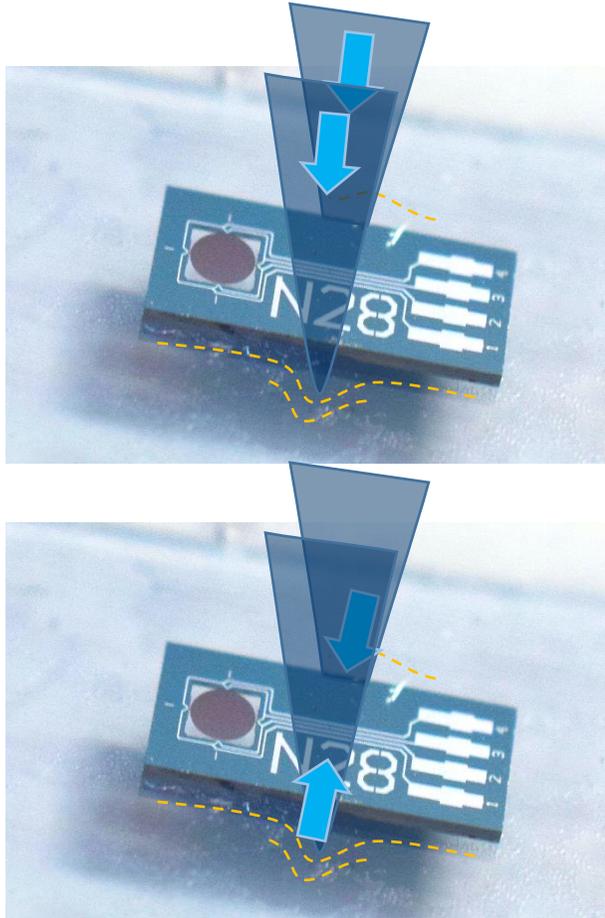


- Compact chip size for tight mounting space
- Platform with coil
- Two individual piezoresistive cantilevers
- 3 reference resistors
- Aluminum pads (SD-MSS-1KPMAl), Gold pads (SD-MSS-1KPMAlu)

SD-MSS-1KPMAlu



To remove the chip from gel sheet, it is recommended to use a sharp plastic tweezers.



- (1) Carefully push the tips of tweezers into the gel sheet, like to create a little space in between the chip back and the gel sheet. Don't clamp the chip at this step.
- (2) Slowly move the tips laterally and clamp the chip. Carefully pick up the chip.

Example: SIPEL 1315-SA



If the tips are too sharp, make them blunt.

SD-MSS-1KPMAl

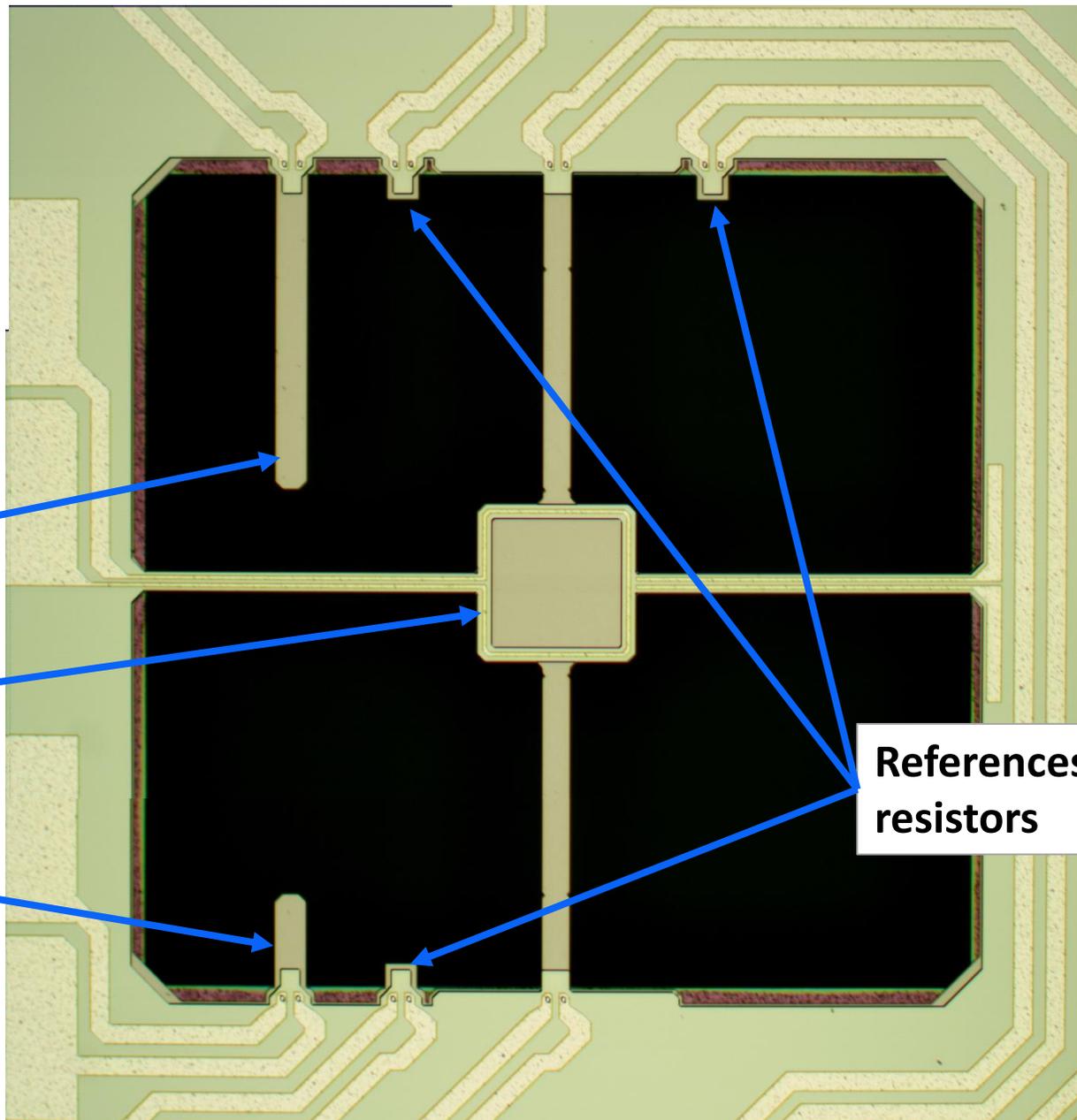
SD-MSS-1KPMAu

Piezoresistive
cantilever 400 μm

Torsional platform
with coil

Piezoresistive
cantilever 120 μm

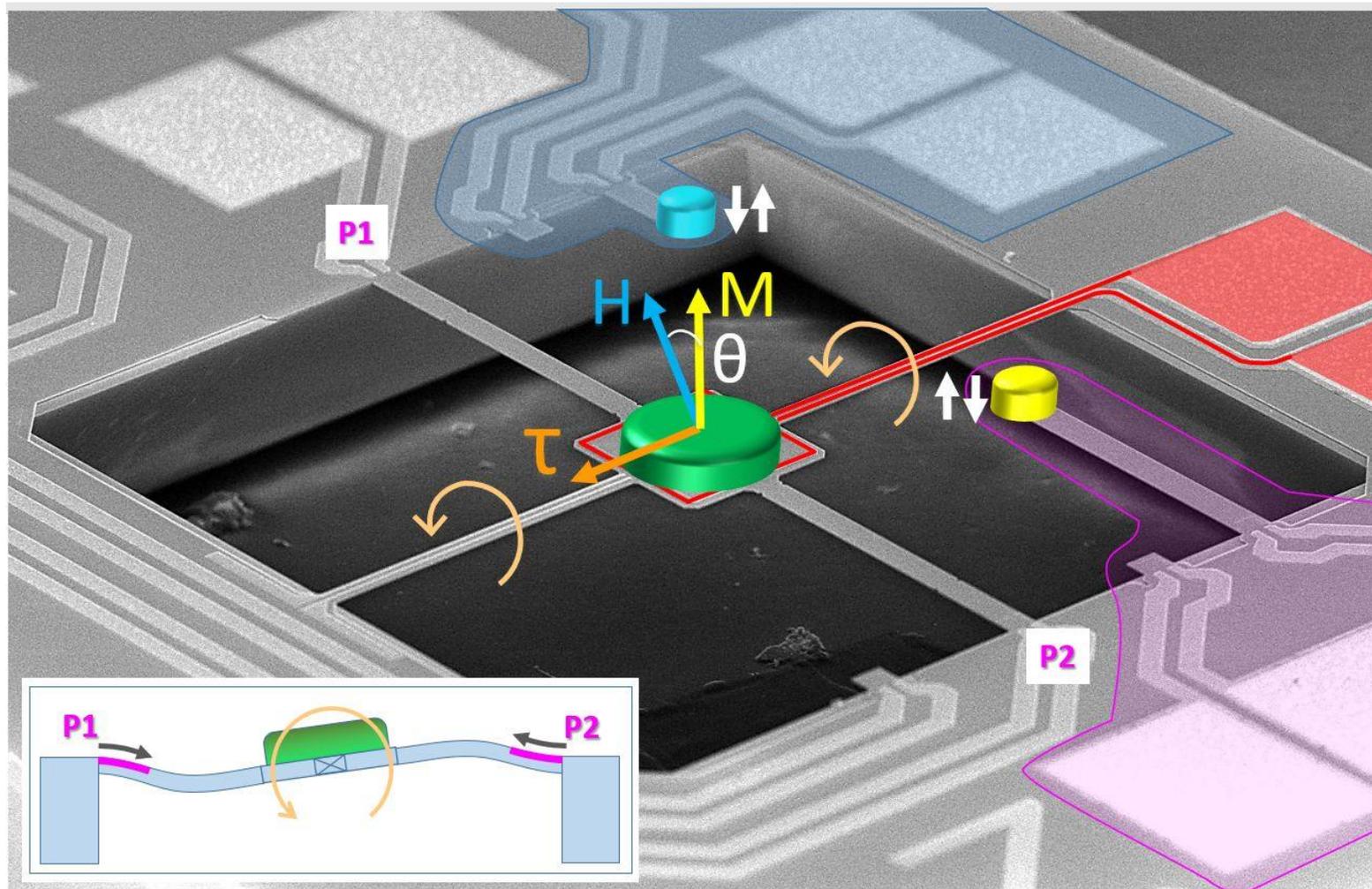
References
resistors



SD-MSS-1KPMAl

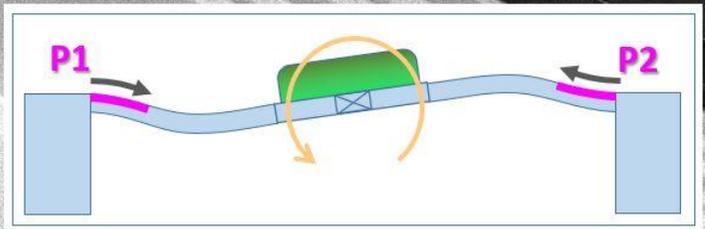
SD-MSS-1KPMAlu

Piezoresistive cantilever 120 μm



Coil for calibration

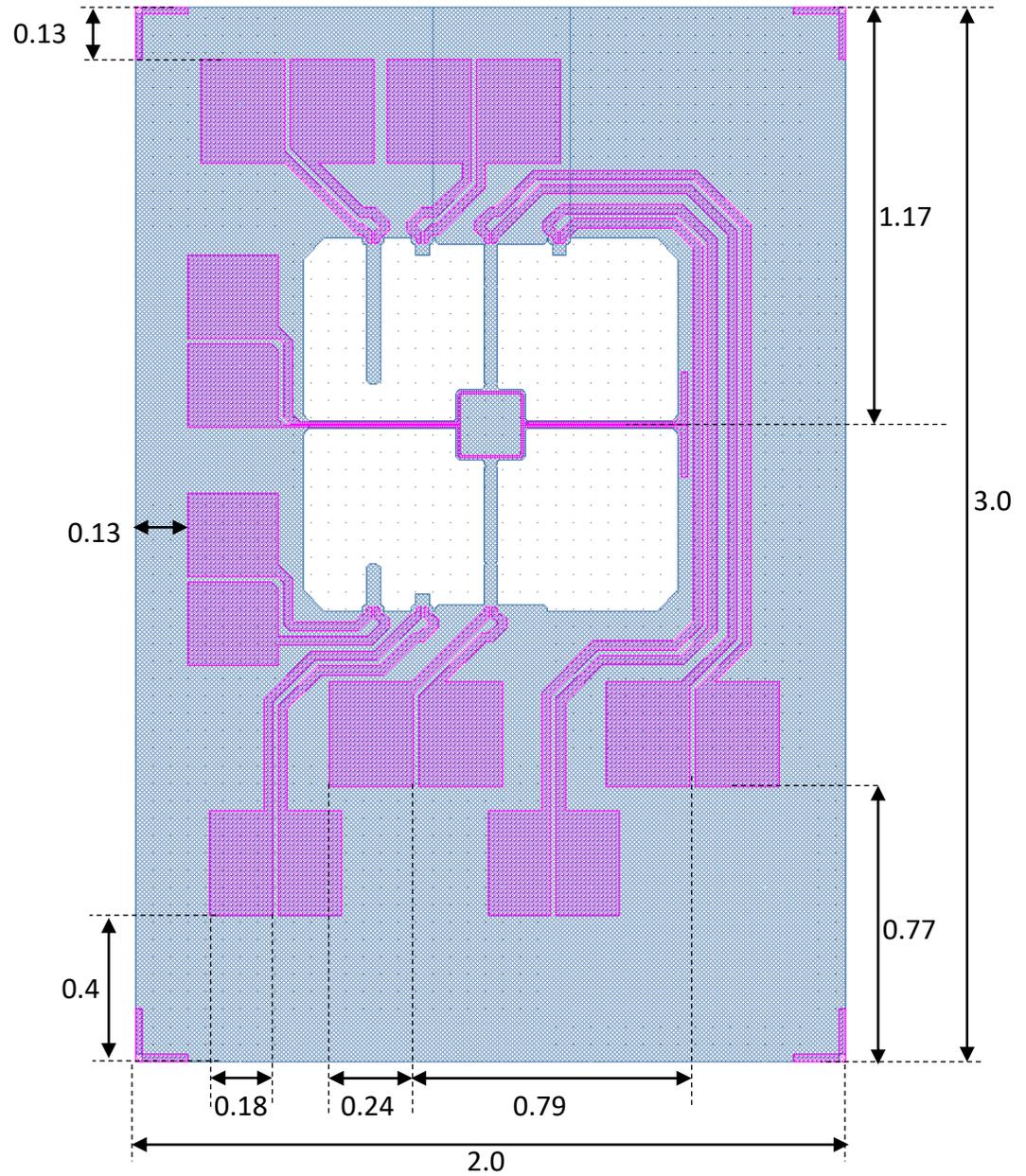
Piezoresistive cantilever 400 μm



Dimensions

SD-MSS-1KPMAl

SD-MSS-1KPMAu

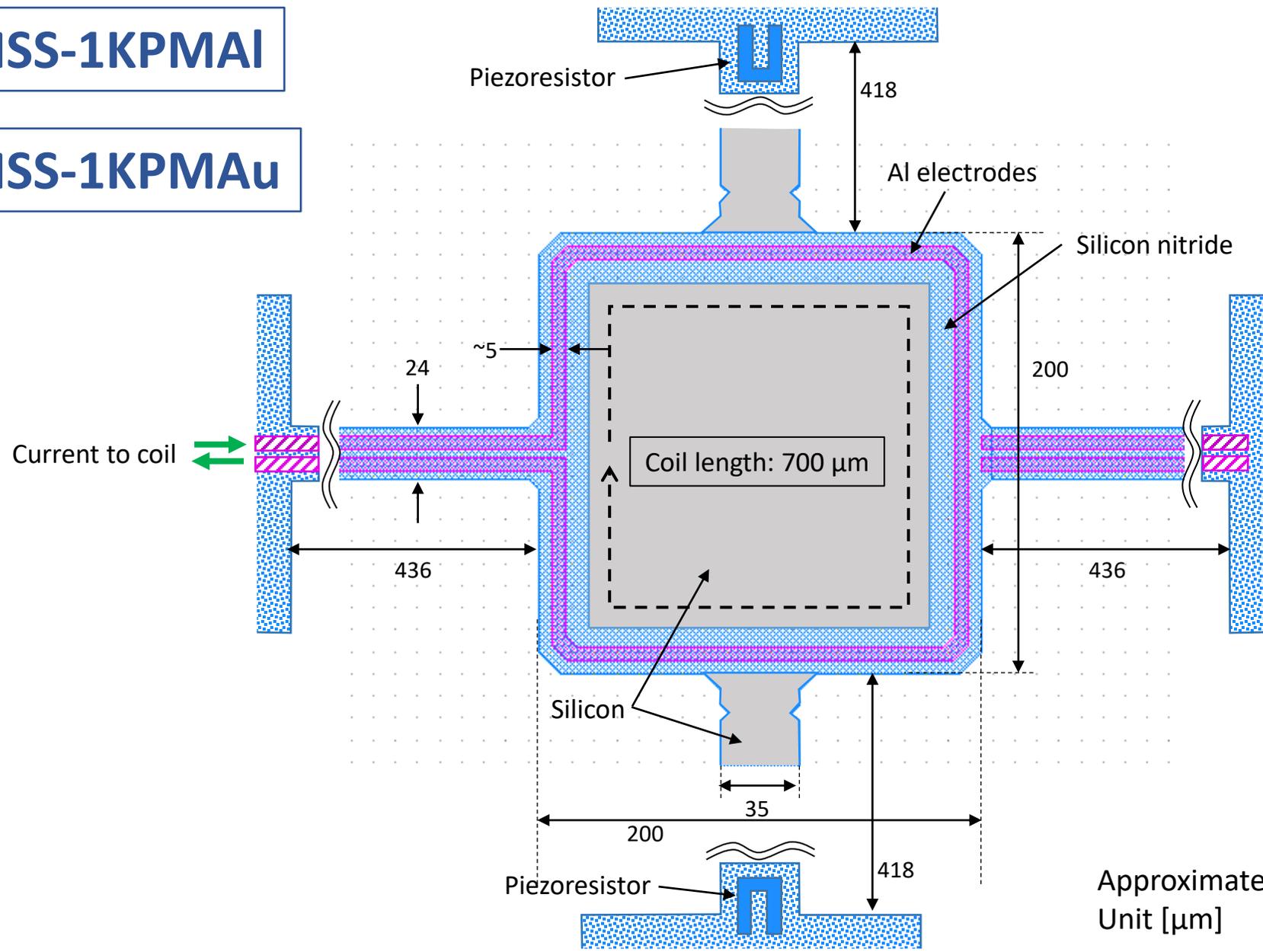


The chip thickness is approximately 0.3 mm.

Approximate values, Unit [mm]

SD-MSS-1KPMAl

SD-MSS-1KPMAu



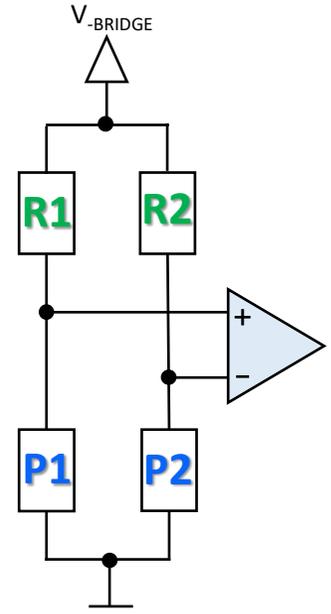
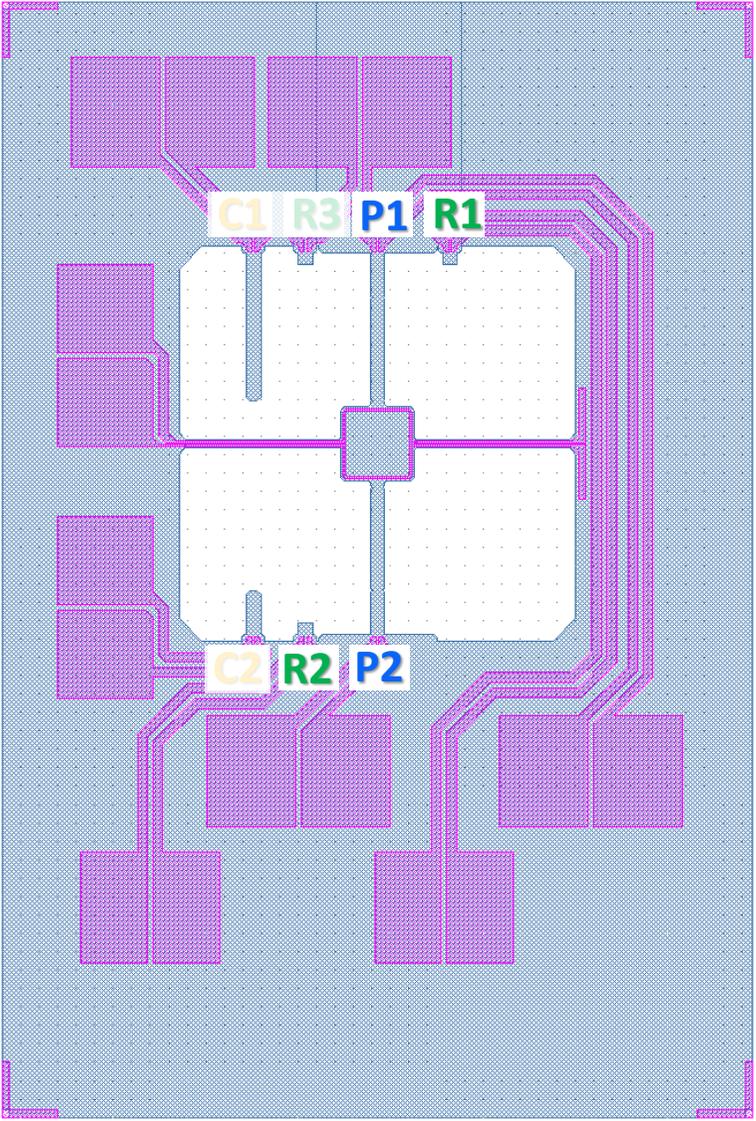
Approximate values
Unit [μm]

SD-MSS-1KPMAl

SD-MSS-1KPMAu

C1 C2
P1 P2
R1 R2 R3

All piezoresistors are identical.



If the potential of the silicon part should be 0V, the bridge voltage must be negative ($V_{BRIDGE} < 0V$).

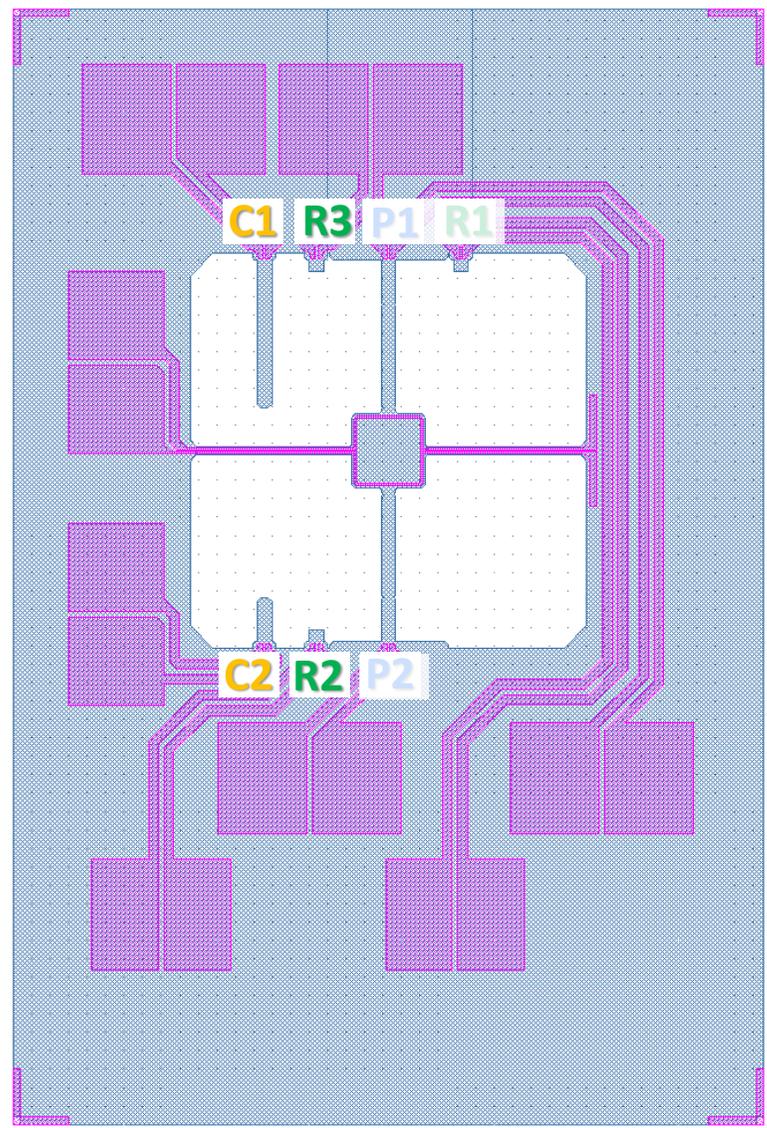
This is because the piezoresistors are p-type diffusions on n-type substrate and the potential of the silicon part becomes the highest potential available on the chip.

SD-MSS-1KPMAl

SD-MSS-1KPMAu

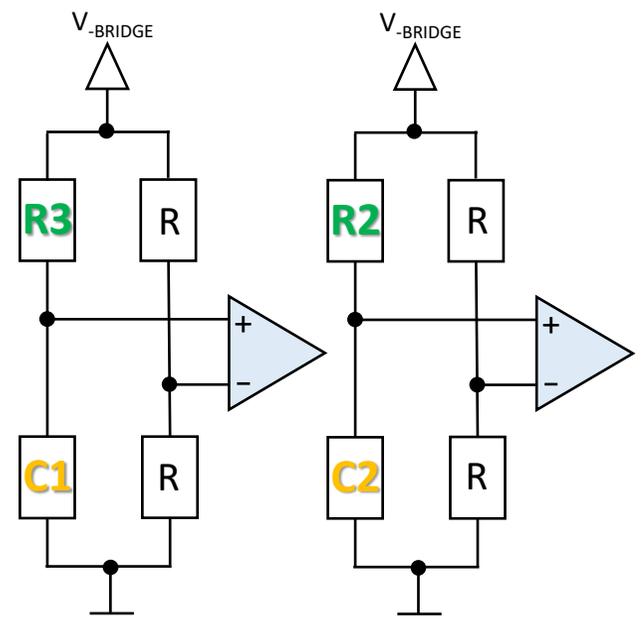
C1 C2
P1 P2
R1 R2 R3

All piezoresistors are identical.



400 μm

120 μm

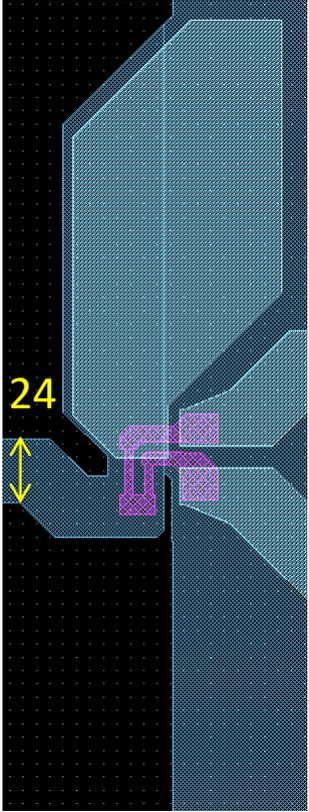
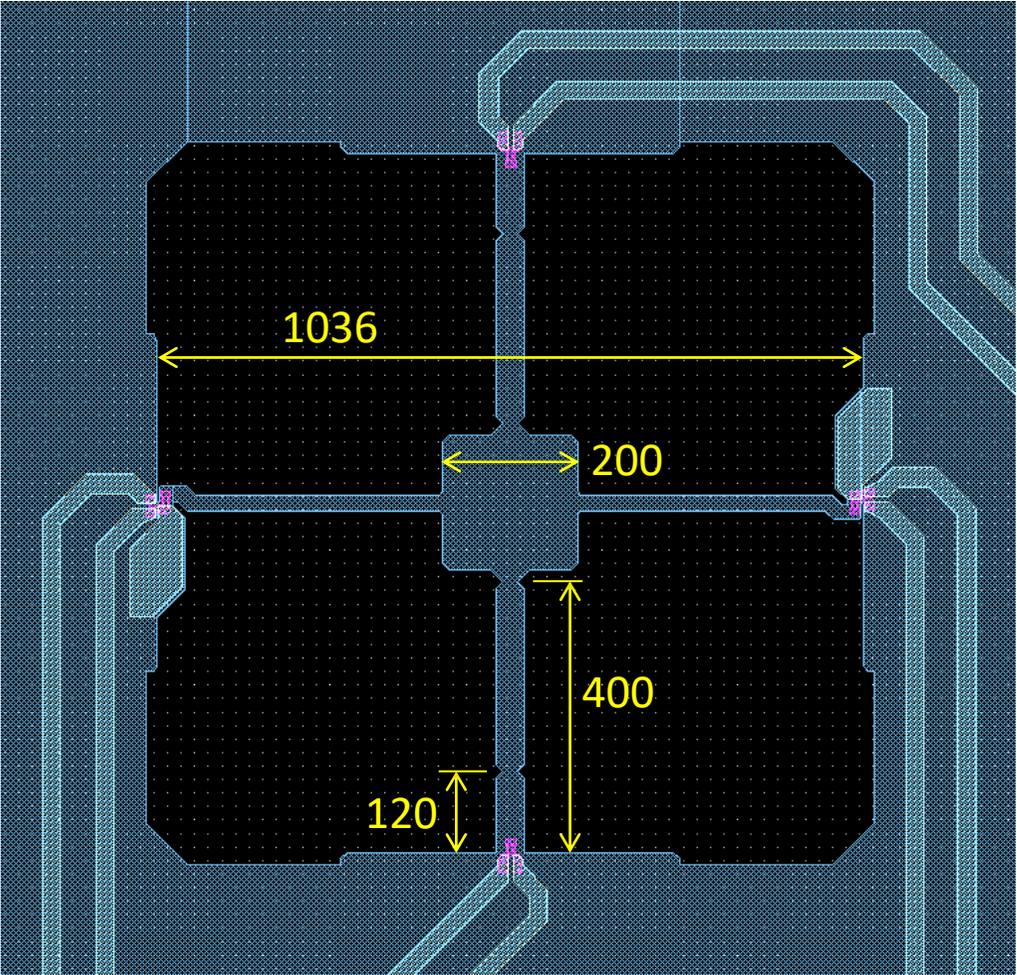
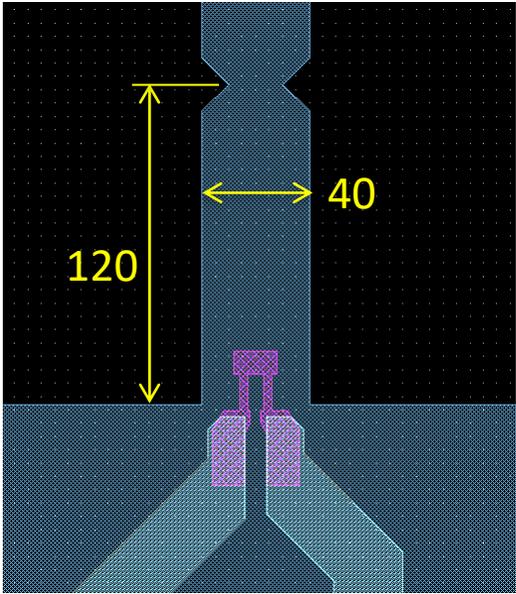


R: external resistor

If the potential of the silicon part should be 0V, the bridge voltage must be negative ($V_{BRIDGE} < 0V$).

This is because the piezoresistors are p-type diffusions on n-type substrate and the potential of the silicon part becomes the highest potential available on the chip.

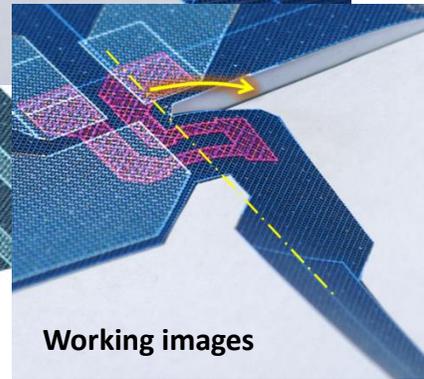
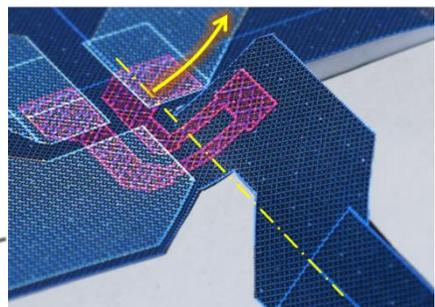
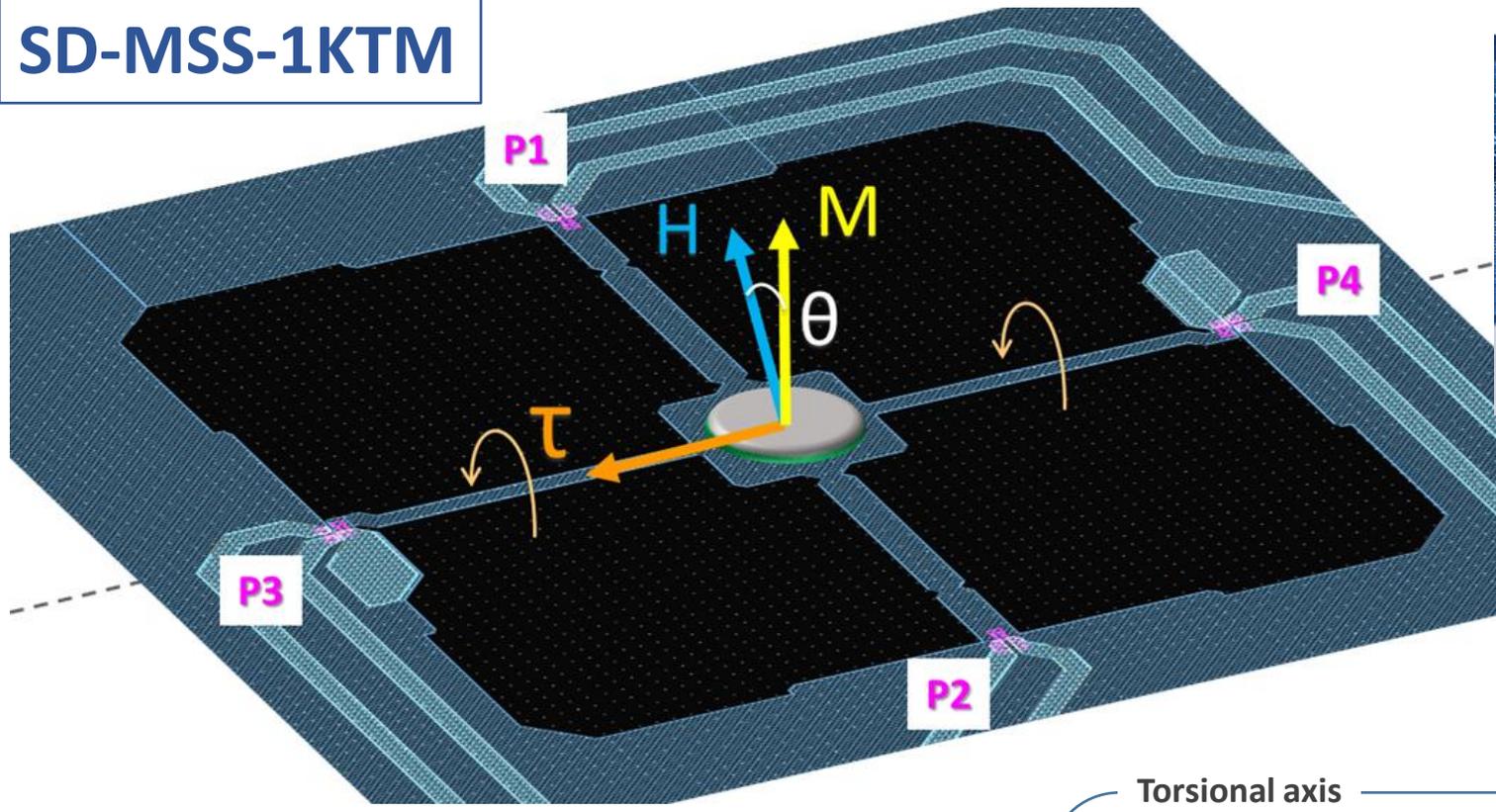
SD-MSS-1KTM



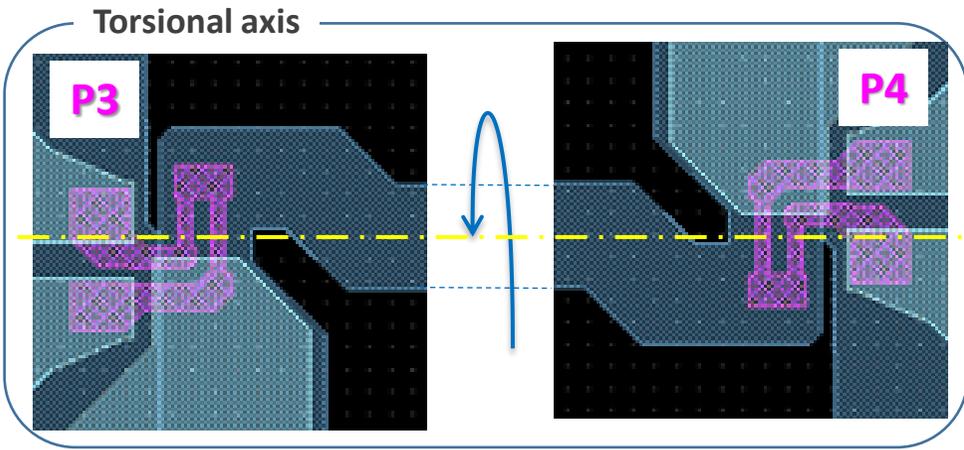
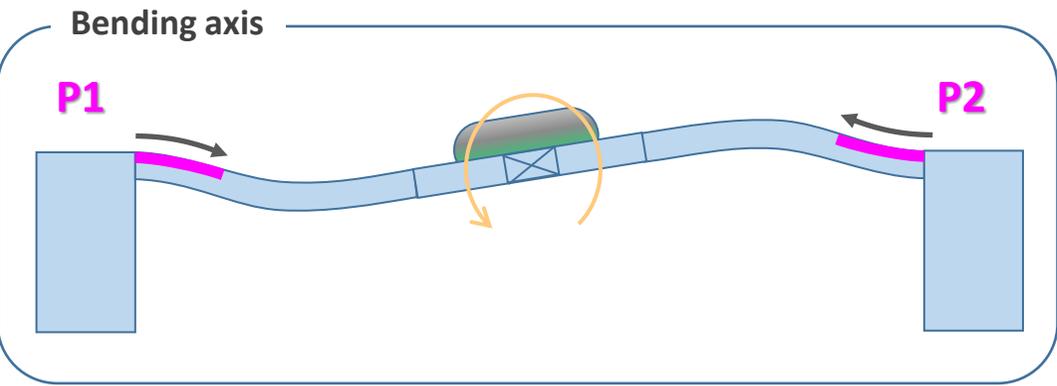
Typical thickness: 2.8 μm

Typical application

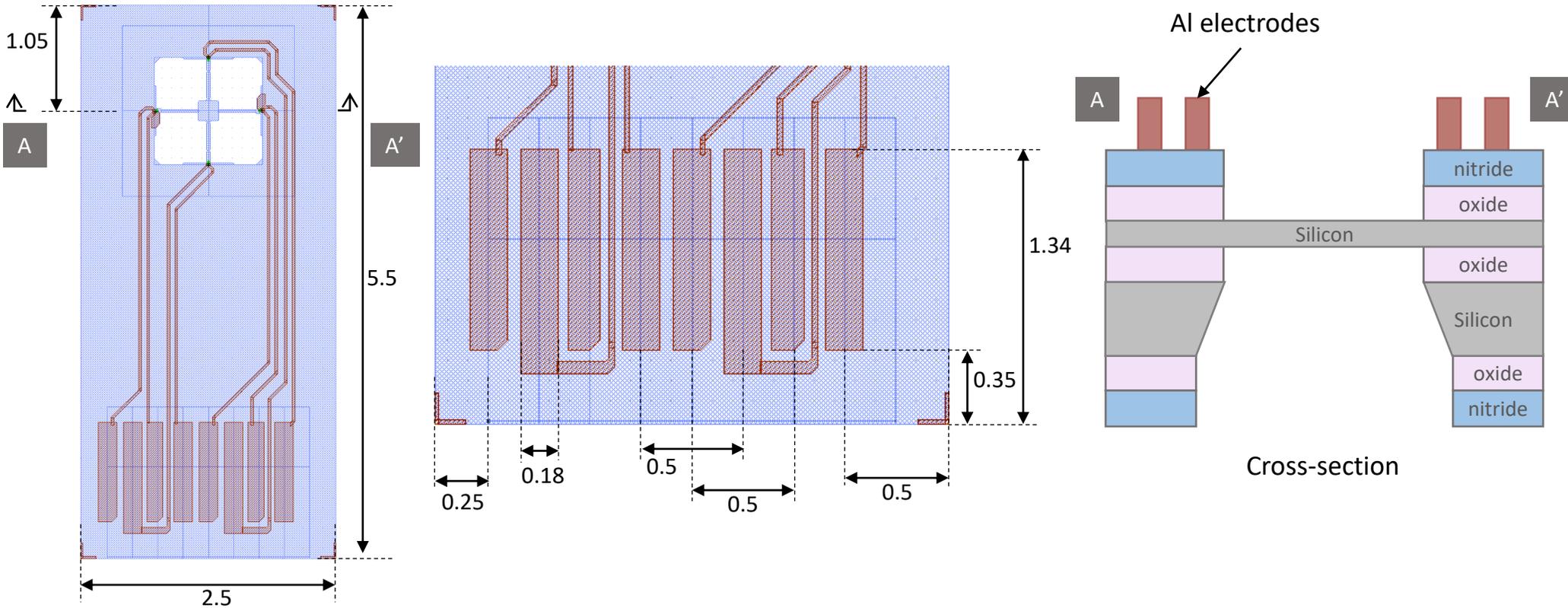
SD-MSS-1KTM



Working images

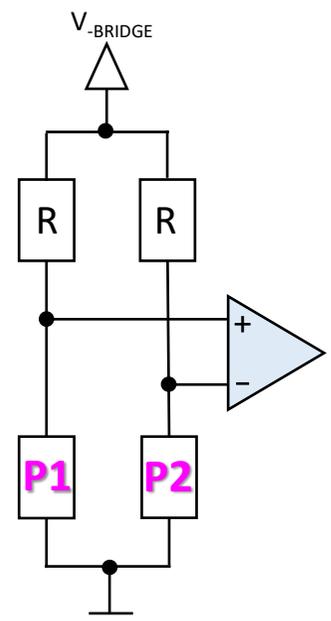
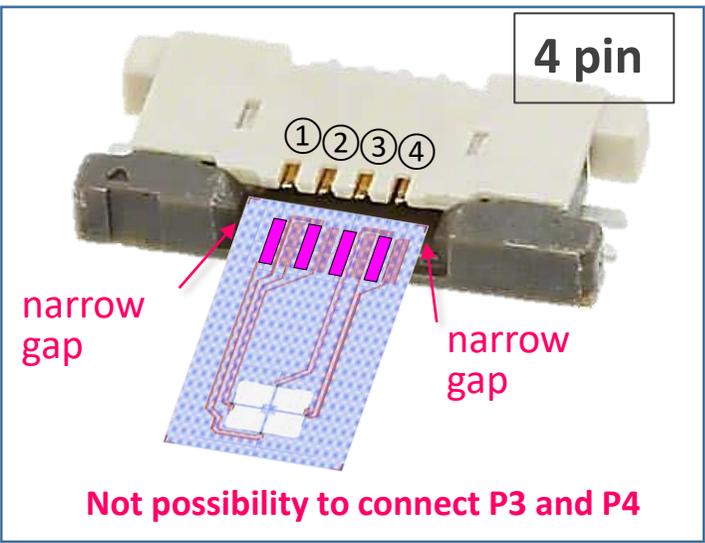
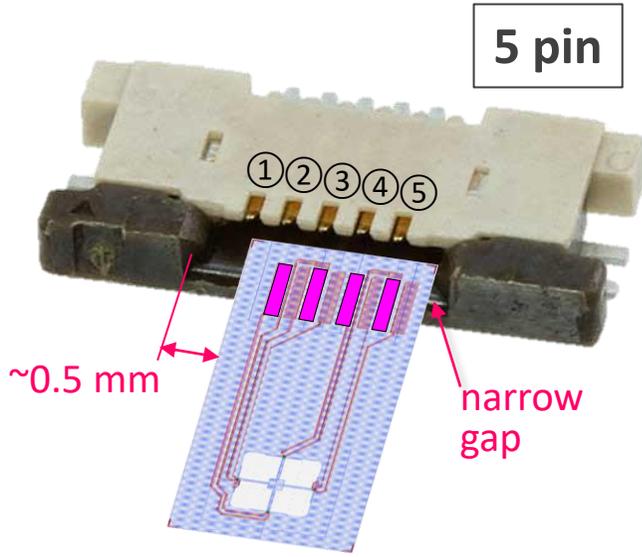
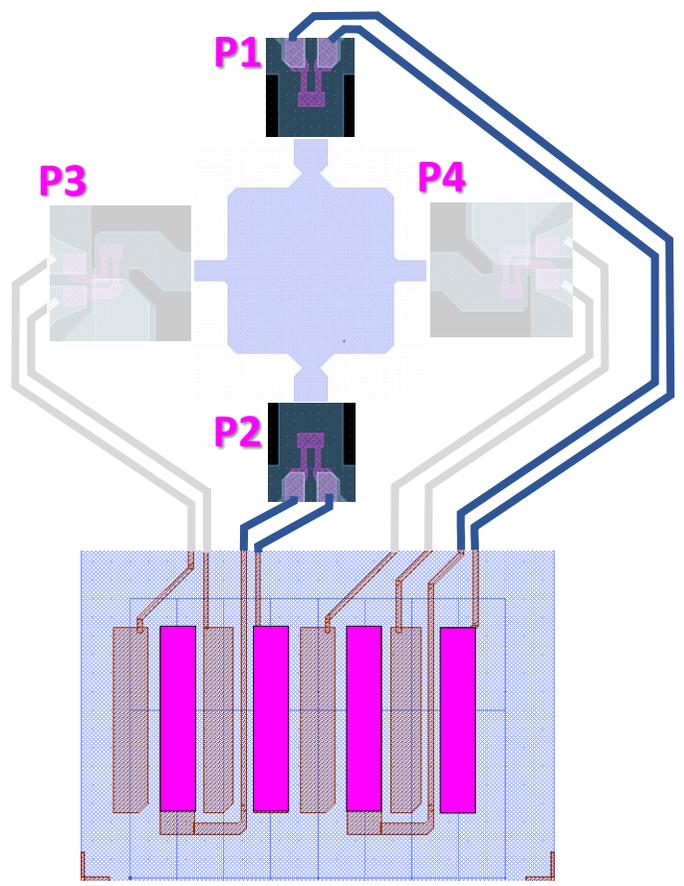


SD-MSS-1KTM



The chip thickness is approximately 0.3 mm.
Approximate values, Unit [mm]

SD-MSS-1K™

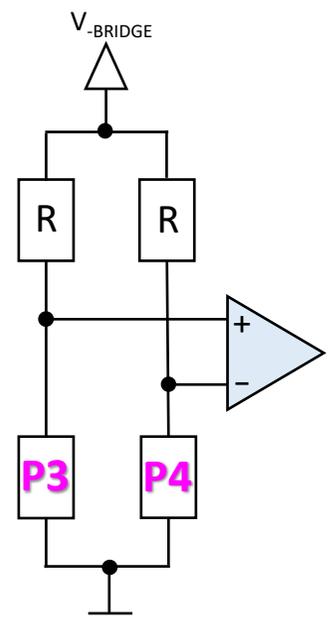
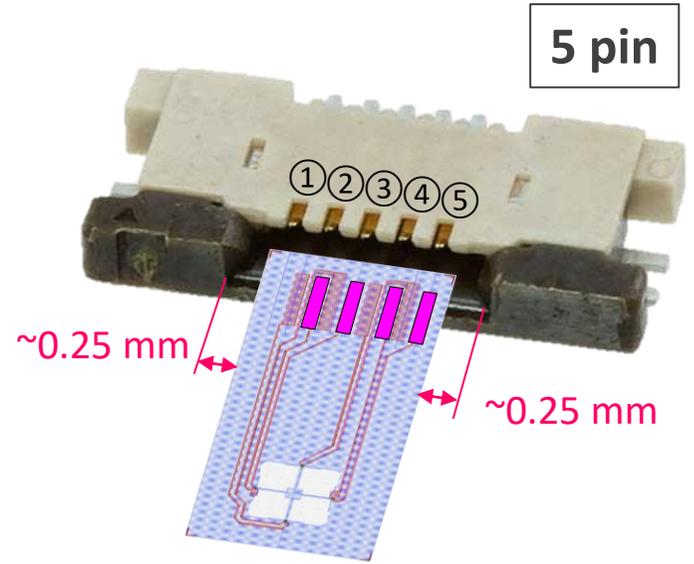
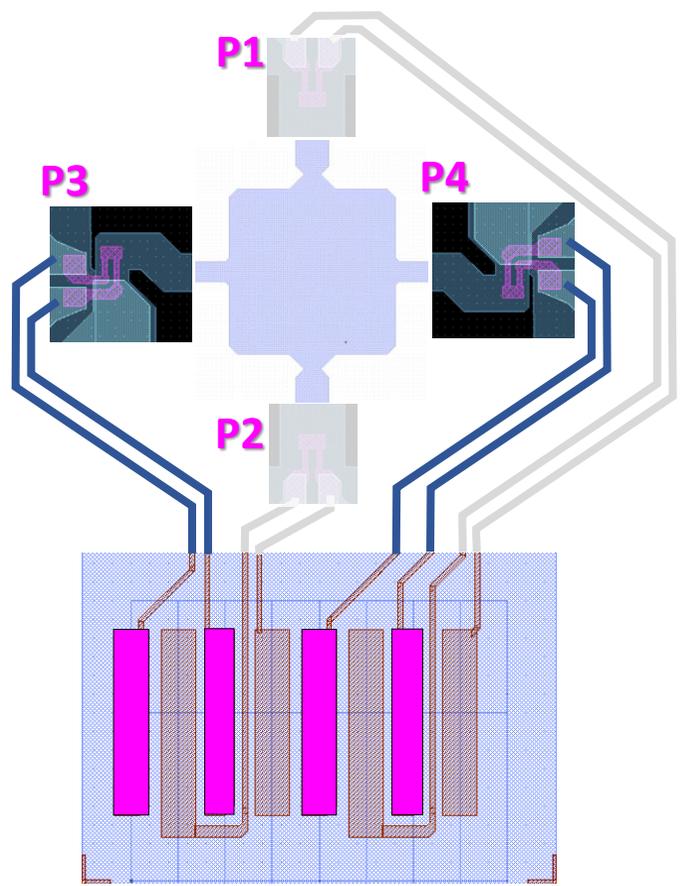


R: external resistor

If the potential of the silicon beams should be 0V, the bridge voltage must be negative ($V_{-BRIDGE} < 0V$).

This is because the piezoresistors are p-type diffusions on n-type substrate and the potential of the silicon part becomes the highest potential available on the chip.

SD-MSS-1K™

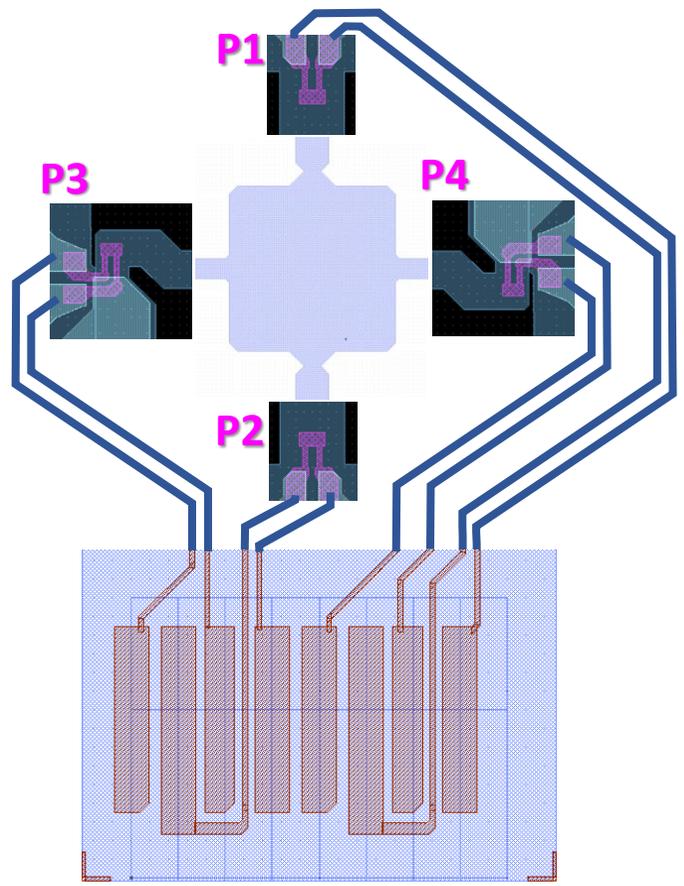


R: external resistor

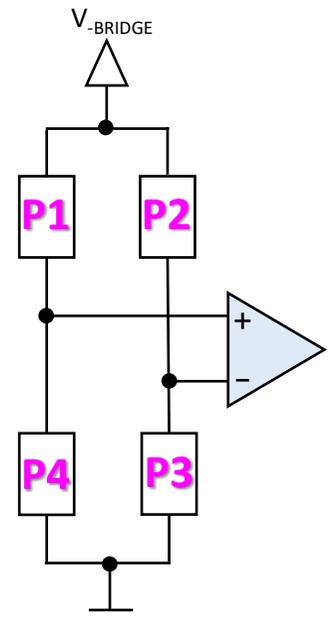
If the potential of the silicon beams should be 0V, the bridge voltage must be negative ($V_{-BRIDGE} < 0V$).

This is because the piezoresistors are p-type diffusions on n-type substrate and the potential of the silicon part becomes the highest potential available on the chip.

SD-MSS-1K™



All pads have to be connected by e.g., wire bonding.

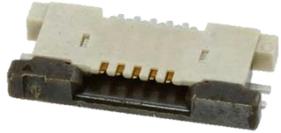


If the potential of the silicon beams should be 0V, the bridge voltage must be negative ($V_{-BRIDGE} < 0V$).

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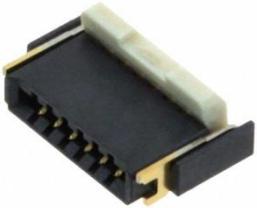
SD-MSS-1KTM

The following connectors are recommended for Torque Magnetometry applications.



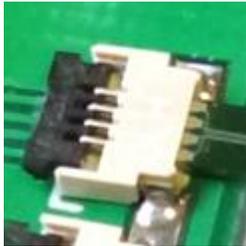
- ❑ Molex 54550 series, e.g., 54550-0471 (4 pin), 54550-0571 (5 pin) : Front slider type. Not simple to fix the chip, but the chip can be strongly clamped. The alignment between the pads on the chip and the connector pins is highly visible. The size of the connector is relatively big.

<http://www.digikey.ch/product-detail/en/molex-llc/0545500471/WM8825CT-ND/3197255>



- ❑ Panasonic Y5B series, e.g., AYF530535A (5 pin) : Back rotary clamp, easy to mount the chip. However, the chip is not strongly clamped compared to the connector mentioned above, which may be problematic in some applications. A big advantage is its compact size.

<https://www.digikey.ch/products/en?keywords=255-5520-nd>



- ❑ Hirose FH34(S) series, e.g., FH34S-4S-0.5SH (4 pin) : Back rotary clamp, easy to mount the chip. This connector has almost the same features as Panasonic one.

[http://www.digikey.ch/product-detail/en/hirose-electric-co-ltd/FH34S-4S-0.5SH\(50\)/HFT104TR-ND/2033607](http://www.digikey.ch/product-detail/en/hirose-electric-co-ltd/FH34S-4S-0.5SH(50)/HFT104TR-ND/2033607)

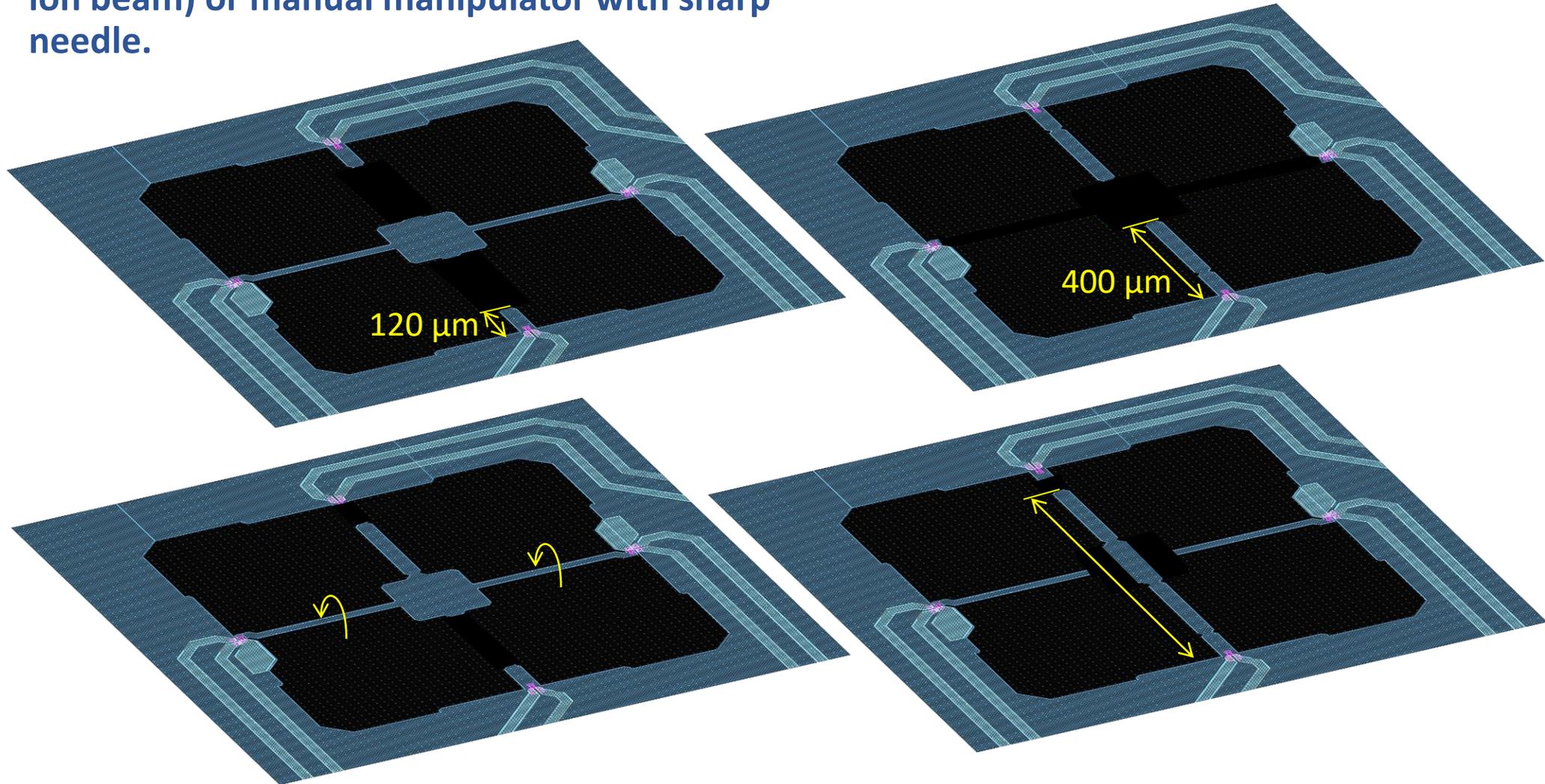
- ❑ Other bland are of course usable if the following conditions are met.

- **FPC (Flexible Printed Circuit)/ FFC (Flexible Flat Cable) connectors**
- **0.5 mm pitch**
- **For 0.3 mm-thick cable**
- **Top, or top&bottom, contact**

SD-MSS-1K™

Breaking (cutting) out of beams by FIB (focused ion beam) or manual manipulator with sharp needle.

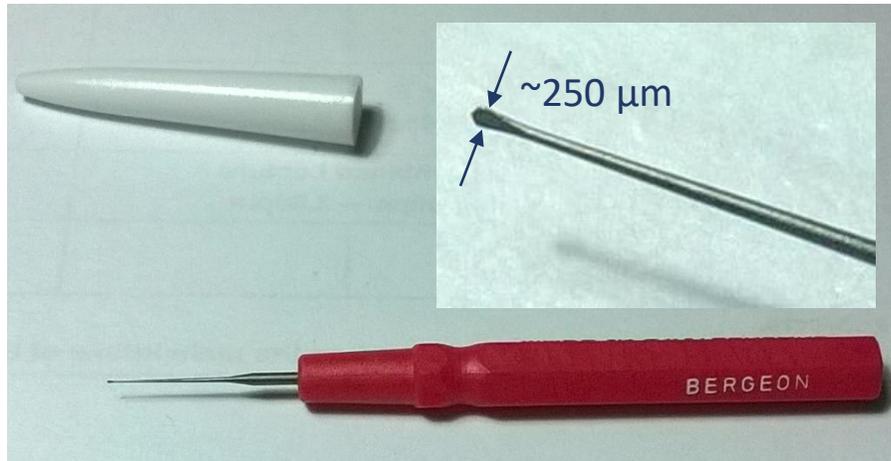
Please do this option at your own risk.



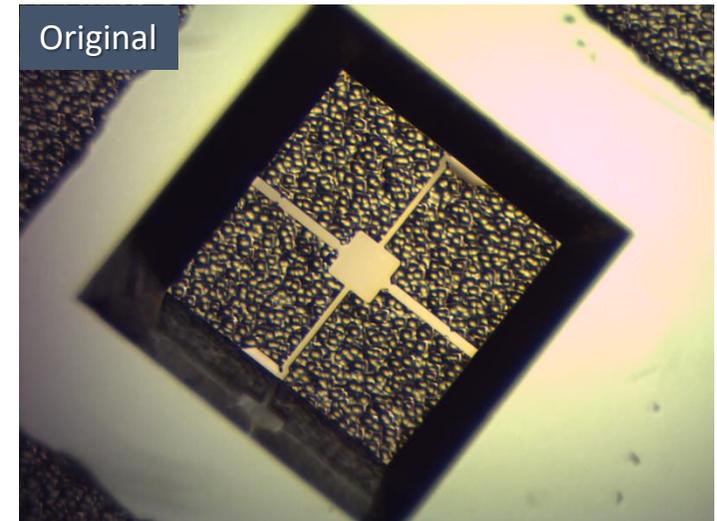
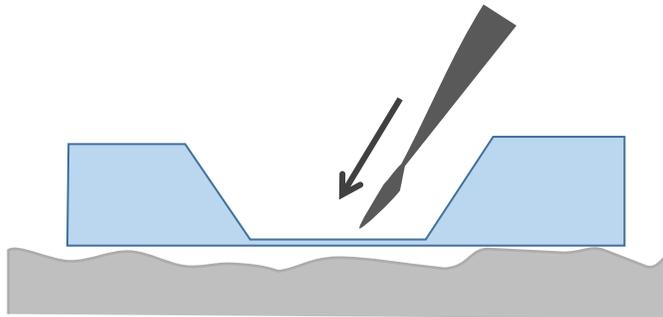
SD-MSS-1K™

Manual breaking of beams is very challenging. However, it's very convenient in some cases and save time.

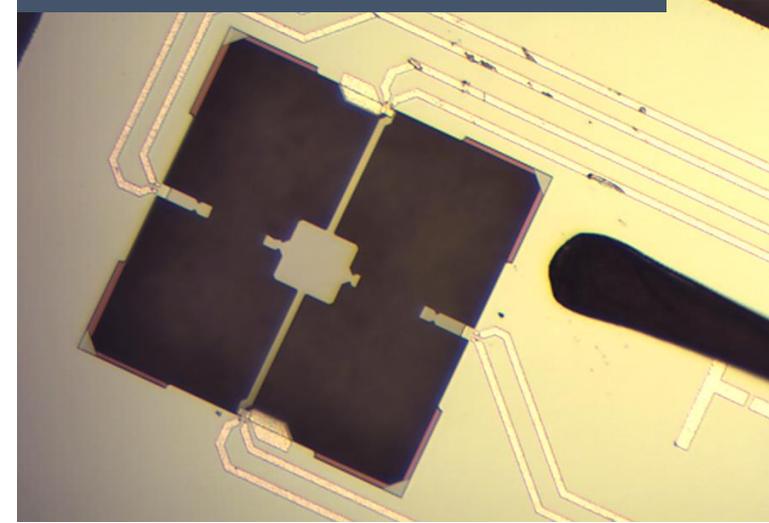
- ❑ Place the chip up-side-down on a rough and hard surface, e.g., back surface of a single-side-polished silicon wafer.
- ❑ Use a sharp needle (e.g., oiler for watchmaker) and poke a beam.



Bergeon 30102-A Oiler (can be purchased on ebay)
(Polishing the flat part of the apex with oil-stone enhances the edge sharpness.)



Result (the needle apex for comparison)



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